

# RJK03P9DPA

MOS1 30 V, 20 A, 7.0 mΩ max.

MOS2 30 V, 50 A, 2.2 mΩ max.

Built in SBD Dual N-channel Power MOS FET

High Speed Power Switching

R07DS0907EJ0110

Rev.1.10

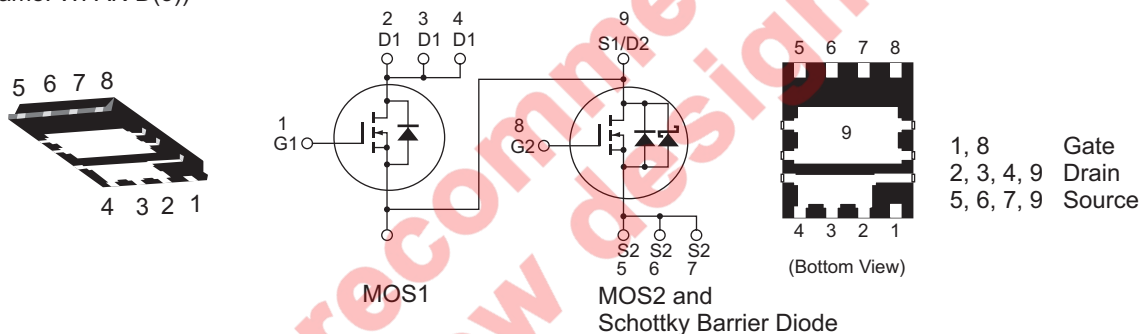
Nov 01, 2012

## Features

- Low on-resistance
- Capable of 4.5 V gate drive
- High density mounting
- Pb-free
- Halogen-free

## Outline

RENESAS Package code: PWSN0008DD-B  
(Package name: WPAK-D(3))



## Absolute Maximum Ratings

(Ta = 25°C)

| Item                    | Symbol                          | Ratings     |             | Unit |
|-------------------------|---------------------------------|-------------|-------------|------|
|                         |                                 | MOS1        | MOS2        |      |
| Drain to source voltage | $V_{DSS}$                       | 30          | 30          | V    |
| Gate to source voltage  | $V_{GSS}$                       | ±20         | ±20         | V    |
| Drain current           | $I_D$                           | 20          | 50          | A    |
| Drain peak current      | $I_{D(pulse)}$ <sup>Note1</sup> | 80          | 200         | A    |
| Reverse drain current   | $I_{DR}$                        | 20          | 50          | A    |
| Avalanche current       | $I_{AP}$ <sup>Note 2</sup>      | 12          | 22          | A    |
| Avalanche energy        | $E_{AS}$ <sup>Note 2</sup>      | 14.4        | 48          | mJ   |
| Channel dissipation     | $P_{ch}$ <sup>Note3</sup>       | 15          | 35          | W    |
| Channel temperature     | $T_{ch}$                        | 150         | 150         | °C   |
| Storage temperature     | $T_{stg}$                       | -55 to +150 | -55 to +150 | °C   |

Notes: 1.  $PW \leq 10 \mu s$ , duty cycle  $\leq 1\%$

2. Value at  $T_{ch} = 25^\circ C$ ,  $R_g \geq 50 \Omega$

3.  $T_c = 25^\circ C$

## Electrical Characteristics

## • MOS1

(Ta = 25°C)

| Item                                       | Symbol        | Min | Typ  | Max       | Unit             | Test Conditions  |
|--|---------------|-----|------|-----------|------------------|--|
| Drain to source breakdown voltage          | $V_{(BR)DSS}$ | 30  | —    | —         | V                | $I_D = 10 \text{ mA}$ , $V_{GS} = 0$   |
| Gate to source leak current                | $I_{GSS}$     | —   | —    | $\pm 0.1$ | $\mu\text{A}$    | $V_{GS} = \pm 20 \text{ V}$ , $V_{DS} = 0$                                   |
| Zero gate voltage drain current            | $I_{DSS}$     | —   | —    | 1         | $\mu\text{A}$    | $V_{DS} = 30 \text{ V}$ , $V_{GS} = 0$                                       |
| Gate to source cutoff voltage              | $V_{GS(off)}$ | 1.2 | —    | 2.5       | V                | $V_{DS} = 10 \text{ V}$ , $I_D = 1 \text{ mA}$                               |
| Static drain to source on state resistance | $R_{DS(on)}$  | —   | 5.8  | 7.0       | $\text{m}\Omega$ | $I_D = 10 \text{ A}$ , $V_{GS} = 10 \text{ V}$ <sup>Note4</sup>              |
|  | $R_{DS(on)}$  | —   | 8.4  | 10.9      | $\text{m}\Omega$ | $I_D = 10 \text{ A}$ , $V_{GS} = 4.5 \text{ V}$ <sup>Note4</sup>             |
| Forward transfer admittance                | $ y_{fs} $    | —   | 35   | —         | S                | $I_D = 10 \text{ A}$ , $V_{DS} = 5 \text{ V}$ <sup>Note4</sup>               |
| Input capacitance                          | $C_{iss}$     | —   | 1180 | 1660      | pF               | $V_{DS} = 10 \text{ V}$  |
| Output capacitance                         | $C_{oss}$     | —   | 252  | —         | pF               | $V_{GS} = 0$   |
| Reverse transfer capacitance               | $C_{rss}$     | —   | 90   | —         | pF               | $f = 1 \text{ MHz}$  |
| Gate Resistance                            | $R_g$         | —   | 1.0  | 2.2       | $\Omega$         |  |
| Total gate charge                          | $Q_g$         | —   | 7.7  | —         | nC               | $V_{DD} = 10 \text{ V}$  |
| Gate to source charge                      | $Q_{gs}$      | —   | 3.3  | —         | nC               | $V_{GS} = 4.5 \text{ V}$   |
| Gate to drain charge                       | $Q_{gd}$      | —   | 2.0  | —         | nC               | $I_D = 20 \text{ A}$   |
| Turn-on delay time                         | $t_{d(on)}$   | —   | 3.8  | —         | ns               | $V_{GS} = 10 \text{ V}$ , $I_D = 10 \text{ A}$                               |
| Rise time                                  | $t_r$         | —   | 3.4  | —         | ns               | $V_{DD} \approx 10 \text{ V}$  |
| Turn-off delay time                        | $t_{d(off)}$  | —   | 13.2 | —         | ns               | $R_L = 1.0 \Omega$   |
| Fall time                                  | $t_f$         | —   | 3.8  | —         | ns               | $R_g = 4.7 \Omega$   |
| Body-drain diode forward voltage           | $V_{DF}$      | —   | 0.83 | 1.08      | V                | $I_F = 20 \text{ A}$ , $V_{GS} = 0$ <sup>Note4</sup>                         |
| Body-drain diode reverse recovery time     | $t_{rr}$      | —   | 9.0  | —         | ns               | $I_F = 20 \text{ A}$ , $V_{GS} = 0$<br>$di_F/dt = 500 \text{ A}/\mu\text{s}$ |

Notes: 4. Pulse test

## • MOS2

(Ta = 25°C)

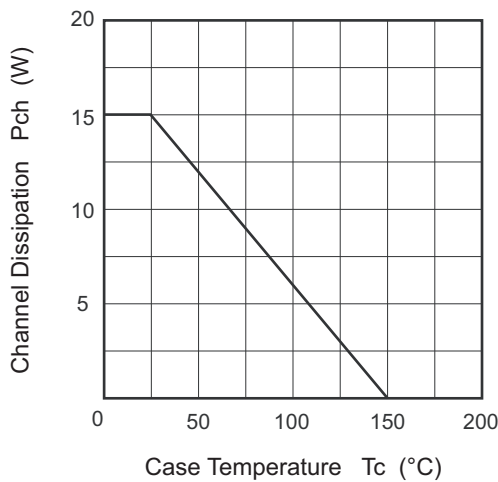
| Item                                       | Symbol        | Min | Typ  | Max       | Unit             | Test Conditions  |
|--|---------------|-----|------|-----------|------------------|--|
| Drain to source breakdown voltage          | $V_{(BR)DSS}$ | 30  | —    | —         | V                | $I_D = 10 \text{ mA}$ , $V_{GS} = 0$   |
| Gate to source leak current                | $I_{GSS}$     | —   | —    | $\pm 0.5$ | $\mu\text{A}$    | $V_{GS} = \pm 20 \text{ V}$ , $V_{DS} = 0$                                   |
| Zero gate voltage drain current            | $I_{DSS}$     | —   | —    | 1         | mA               | $V_{DS} = 24 \text{ V}$ , $V_{GS} = 0$                                       |
| Gate to source cutoff voltage              | $V_{GS(off)}$ | 1.2 | —    | 2.5       | V                | $V_{DS} = 10 \text{ V}$ , $I_D = 1 \text{ mA}$                               |
| Static drain to source on state resistance | $R_{DS(on)}$  | —   | 1.8  | 2.2       | $\text{m}\Omega$ | $I_D = 25 \text{ A}$ , $V_{GS} = 10 \text{ V}$ <sup>Note4</sup>              |
|  | $R_{DS(on)}$  | —   | 2.1  | 2.7       | $\text{m}\Omega$ | $I_D = 25 \text{ A}$ , $V_{GS} = 4.5 \text{ V}$ <sup>Note4</sup>             |
| Forward transfer admittance                | $ y_{fs} $    | —   | 115  | —         | S                | $I_D = 25 \text{ A}$ , $V_{DS} = 5 \text{ V}$ <sup>Note4</sup>               |
| Input capacitance                          | $C_{iss}$     | —   | 4680 | 6560      | pF               | $V_{DS} = 10 \text{ V}$  |
| Output capacitance                         | $C_{oss}$     | —   | 780  | —         | pF               | $V_{GS} = 0$   |
| Reverse transfer capacitance               | $C_{rss}$     | —   | 450  | —         | pF               | $f = 1 \text{ MHz}$  |
| Gate Resistance                            | $R_g$         | —   | 1.3  | 2.6       | $\Omega$         |  |
| Total gate charge                          | $Q_g$         | —   | 36.7 | —         | nC               | $V_{DD} = 10 \text{ V}$  |
| Gate to source charge                      | $Q_{gs}$      | —   | 12.1 | —         | nC               | $V_{GS} = 4.5 \text{ V}$   |
| Gate to drain charge                       | $Q_{gd}$      | —   | 12.1 | —         | nC               | $I_D = 50 \text{ A}$   |
| Turn-on delay time                         | $t_{d(on)}$   | —   | 8.0  | —         | ns               | $V_{GS} = 10 \text{ V}$ , $I_D = 25 \text{ A}$                               |
| Rise time                                  | $t_r$         | —   | 6.0  | —         | ns               | $V_{DD} \approx 10 \text{ V}$  |
| Turn-off delay time                        | $t_{d(off)}$  | —   | 76.4 | —         | ns               | $R_L = 0.4 \Omega$   |
| Fall time                                  | $t_f$         | —   | 24.8 | —         | ns               | $R_g = 4.7 \Omega$   |
| Schottky Barrier diode forward voltage     | $V_F$         | —   | 0.40 | —         | V                | $I_F = 2 \text{ A}$ , $V_{GS} = 0$ <sup>Note4</sup>                          |
| Body-drain diode reverse recovery time     | $t_{rr}$      | —   | 10.0 | —         | ns               | $I_F = 50 \text{ A}$ , $V_{GS} = 0$<br>$di_F/dt = 500 \text{ A}/\mu\text{s}$ |

Notes: 4. Pulse

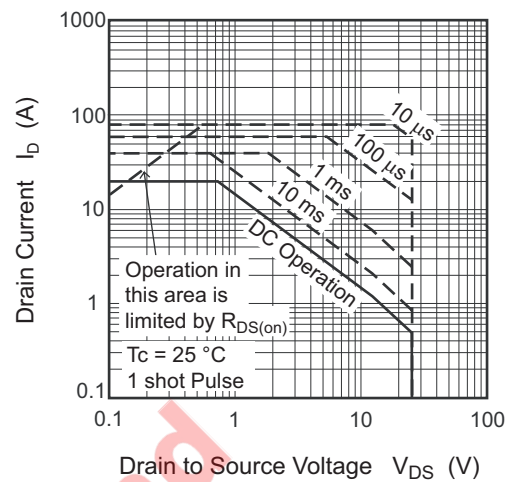
## Main Characteristics

## • MOS1

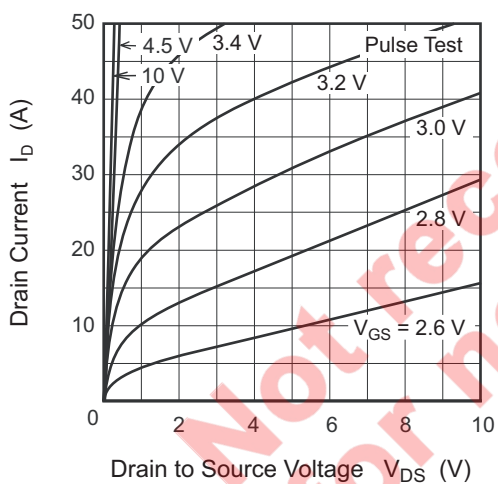
Power vs. Temperature Derating



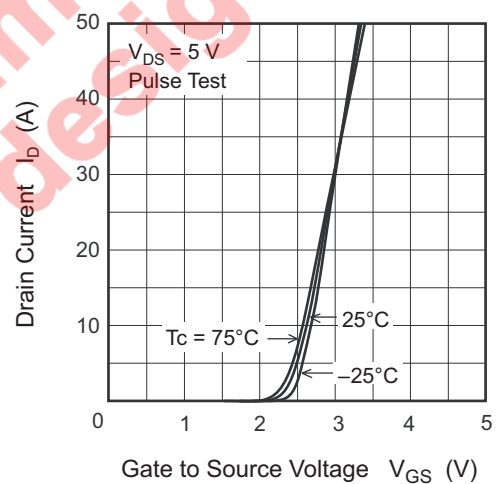
Maximum Safe Operation Area



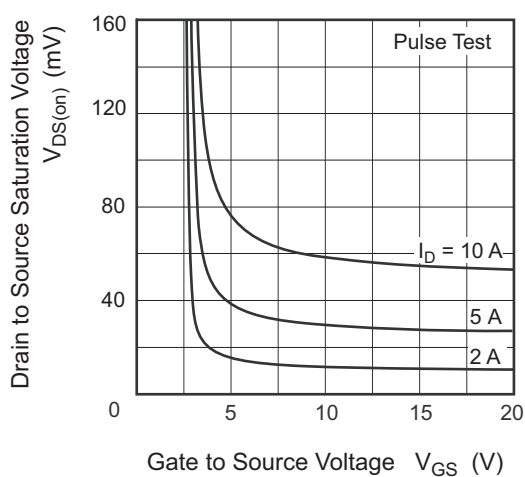
Typical Output Characteristics



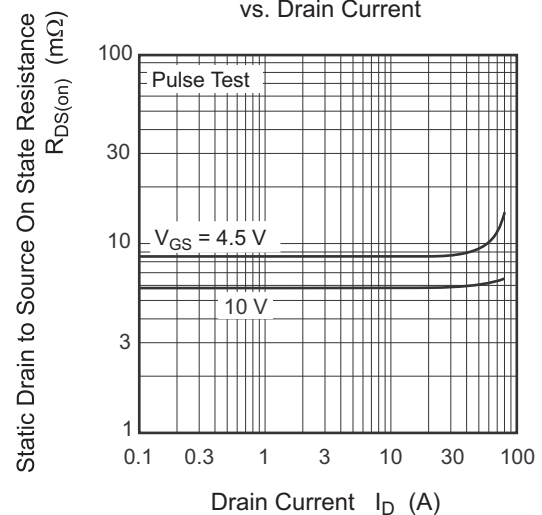
Typical Transfer Characteristics

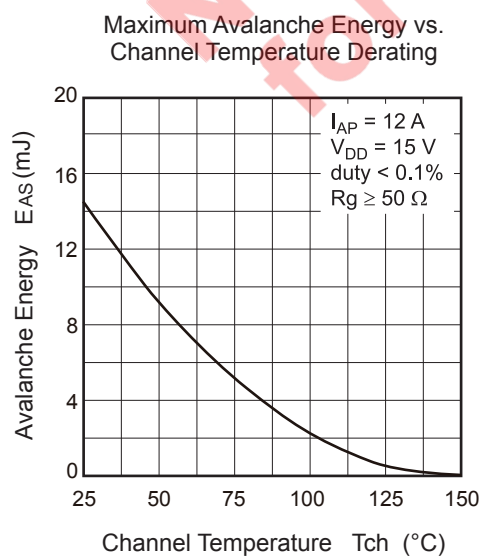
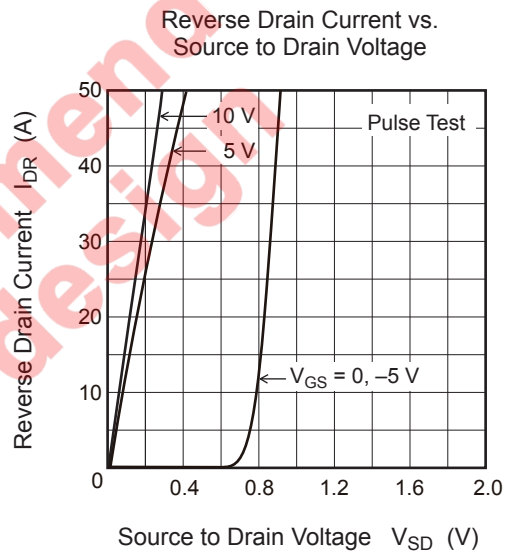
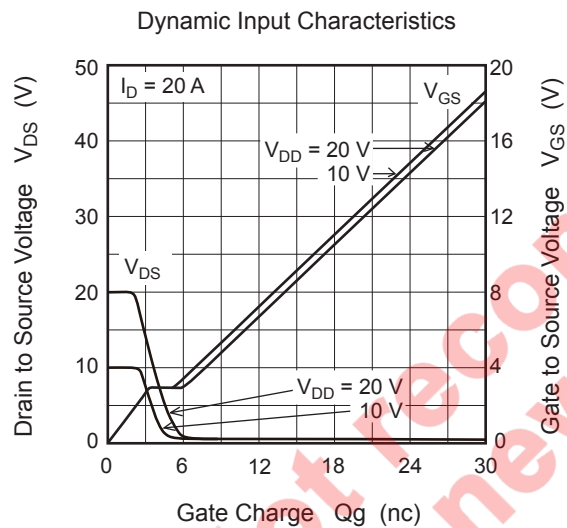
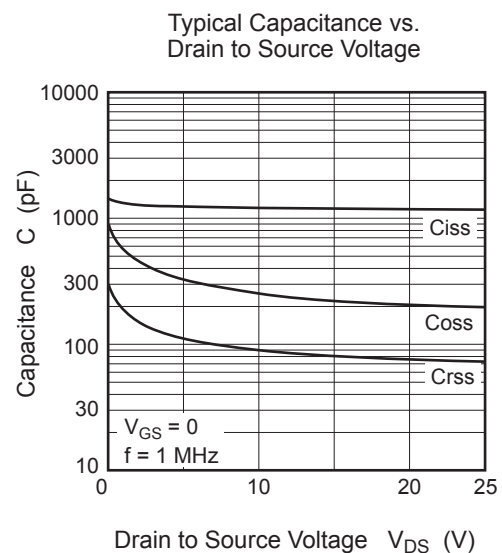
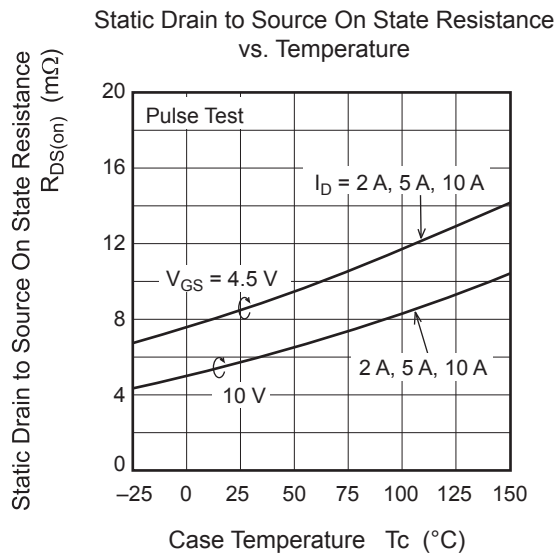


Drain to Source Saturation Voltage vs. Gate to Source Voltage

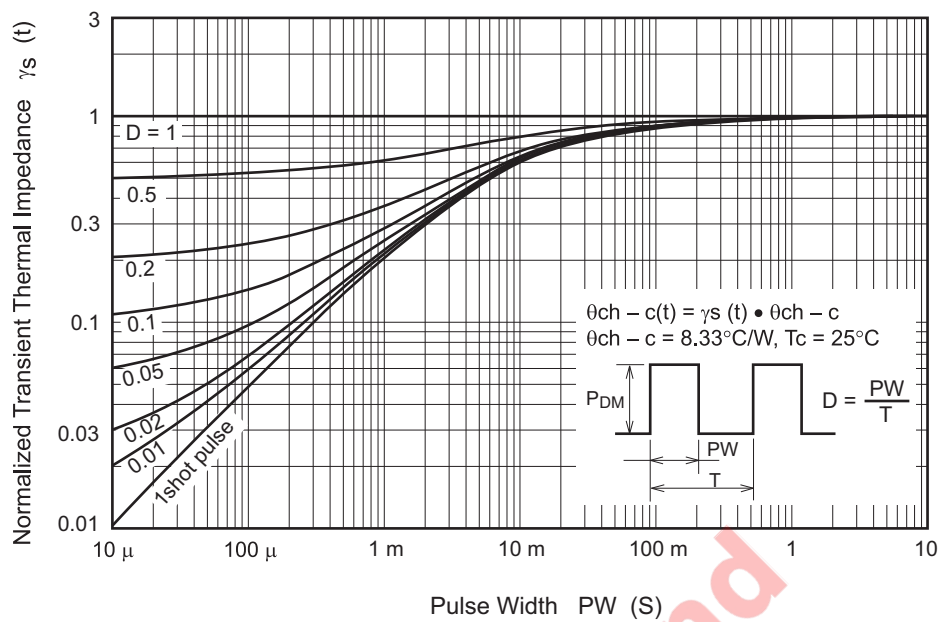


Static Drain to Source On State Resistance vs. Drain Current

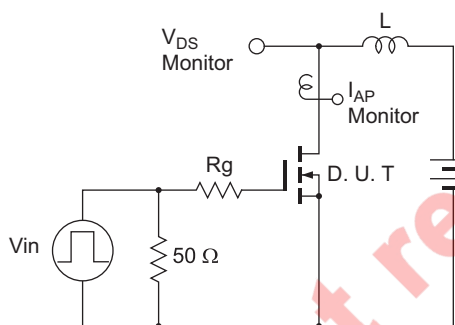




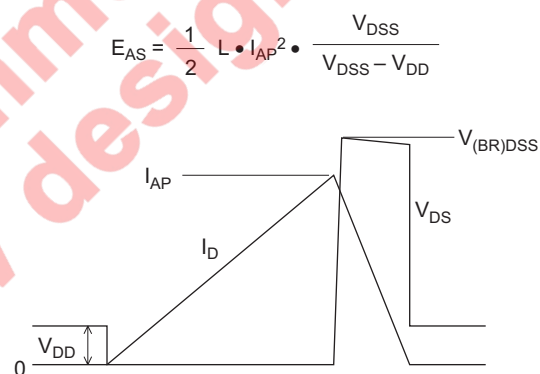
Normalized Transient Thermal Impedance vs. Pulse Width



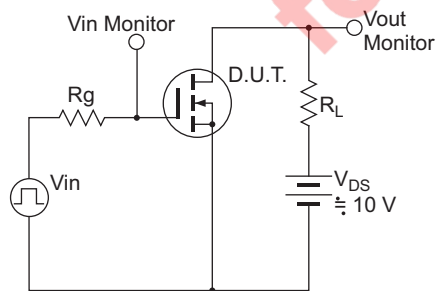
Avalanche Test Circuit



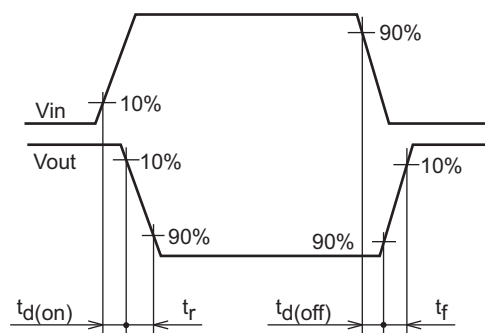
Avalanche Waveform



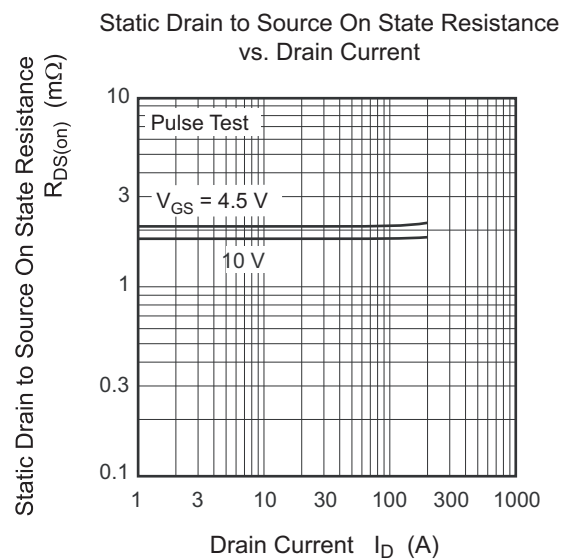
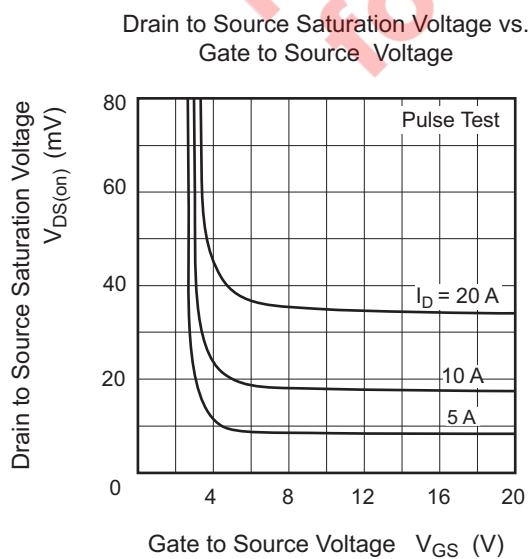
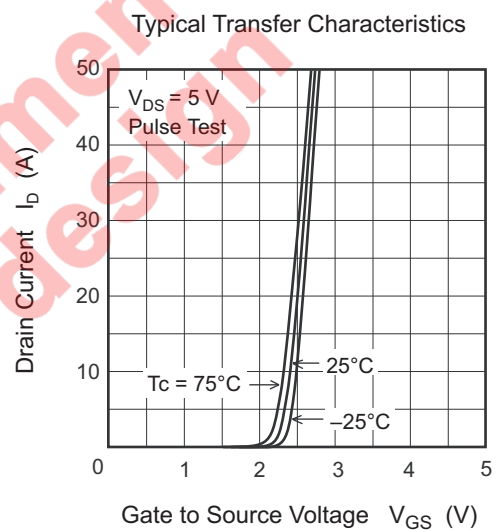
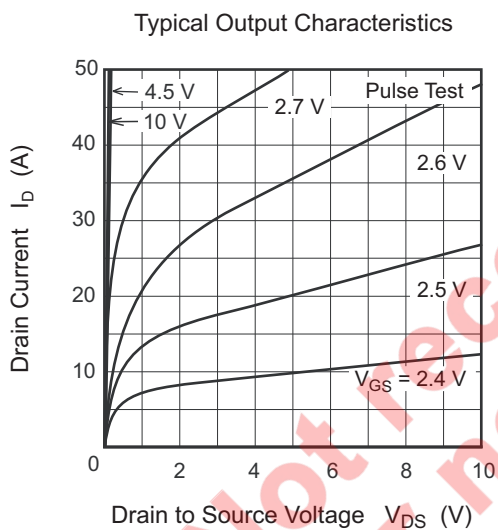
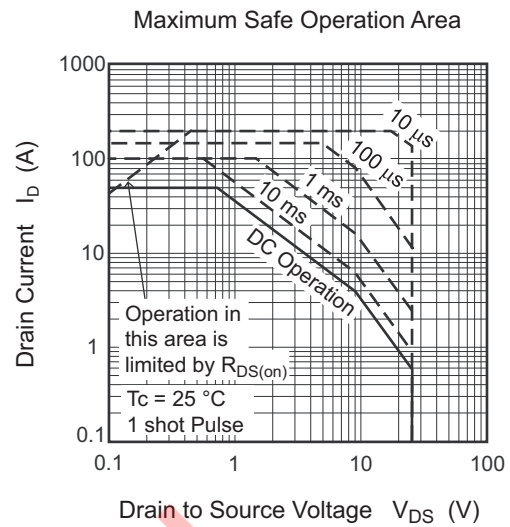
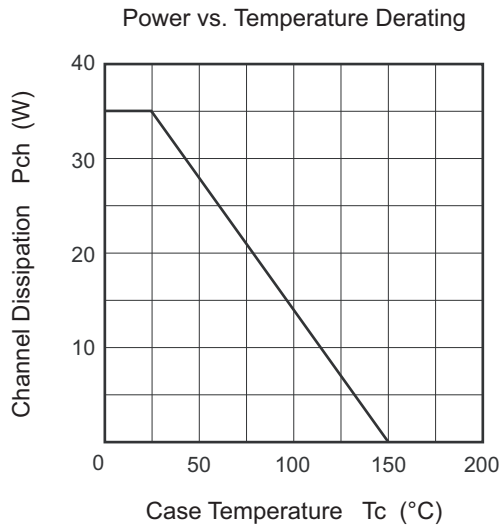
Switching Time Test Circuit



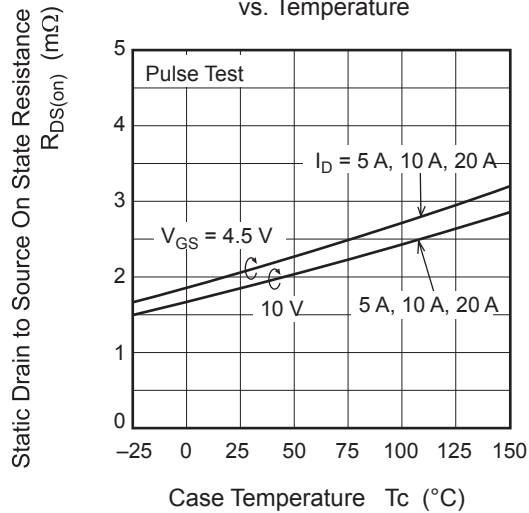
Switching Time Waveform



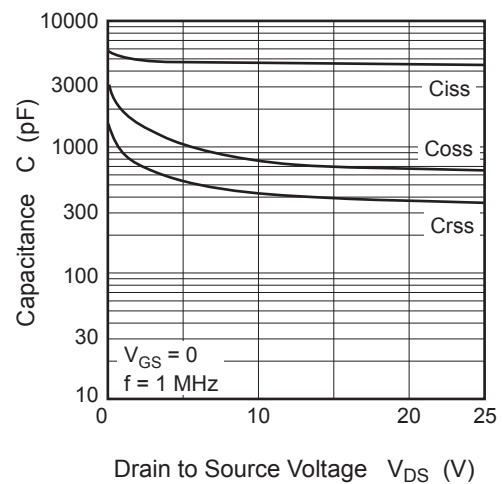
# • MOS2 and Schottky Barrier Diode



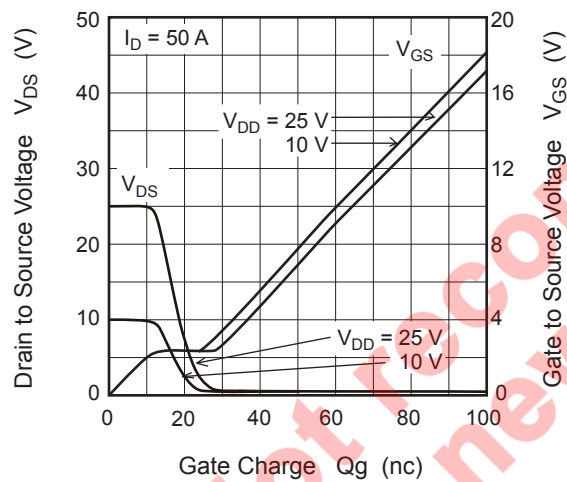
Static Drain to Source On State Resistance vs. Temperature



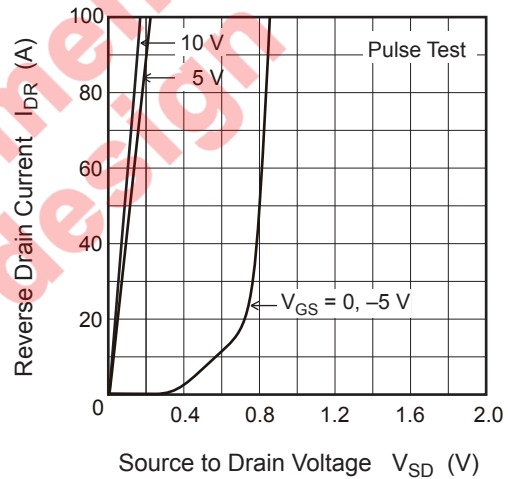
Typical Capacitance vs. Drain to Source Voltage



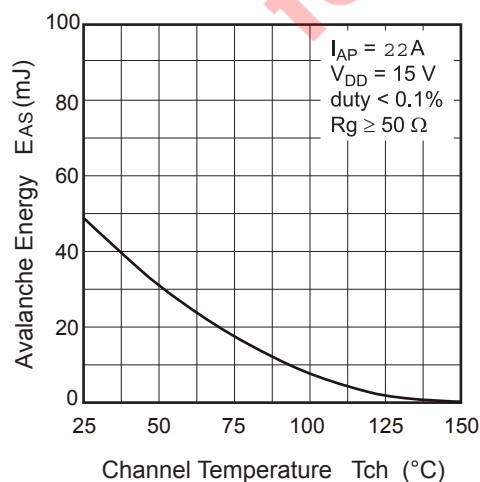
Dynamic Input Characteristics



Reverse Drain Current vs. Source to Drain Voltage

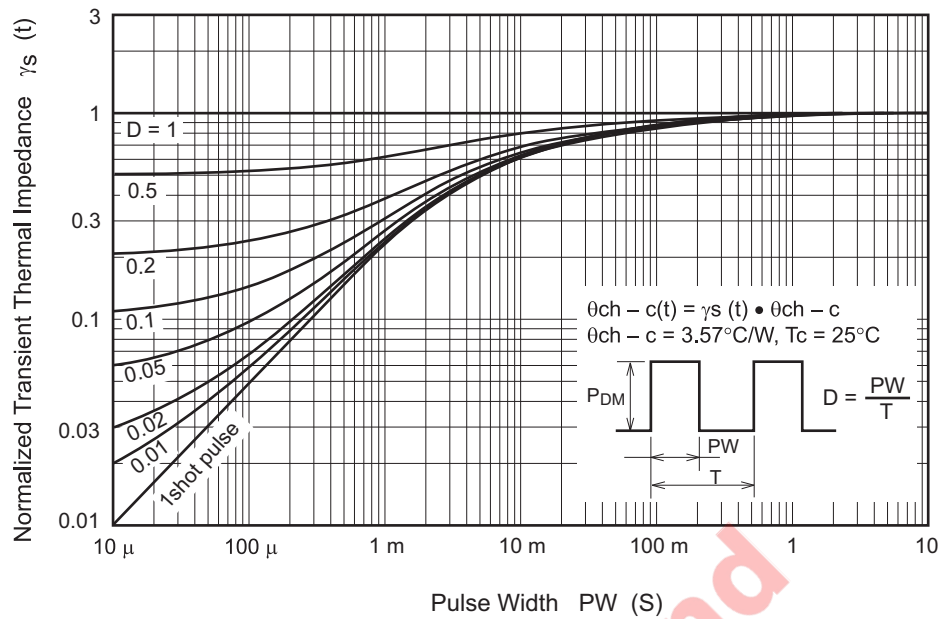


Maximum Avalanche Energy vs. Channel Temperature Derating

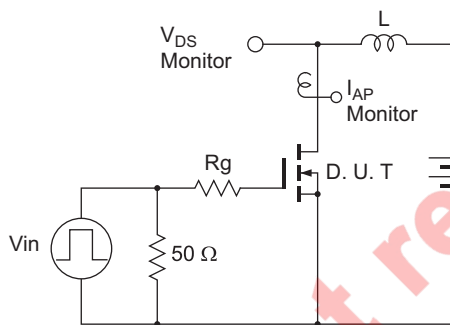




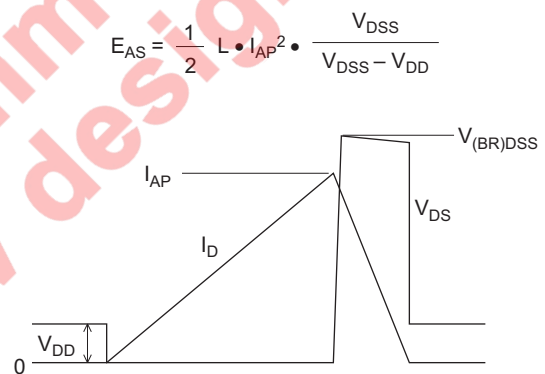
Normalized Transient Thermal Impedance vs. Pulse Width



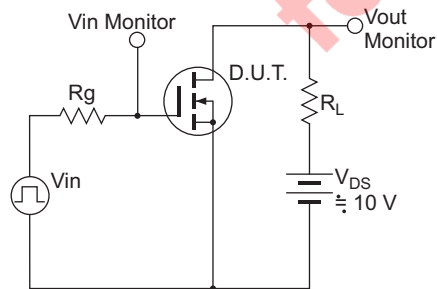
Avalanche Test Circuit



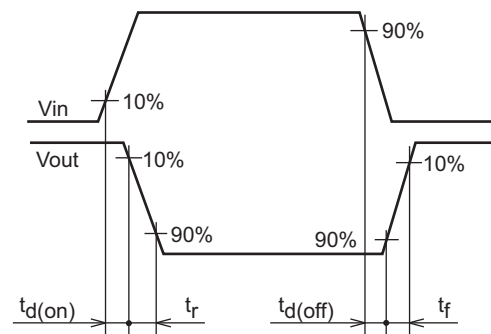
Avalanche Waveform



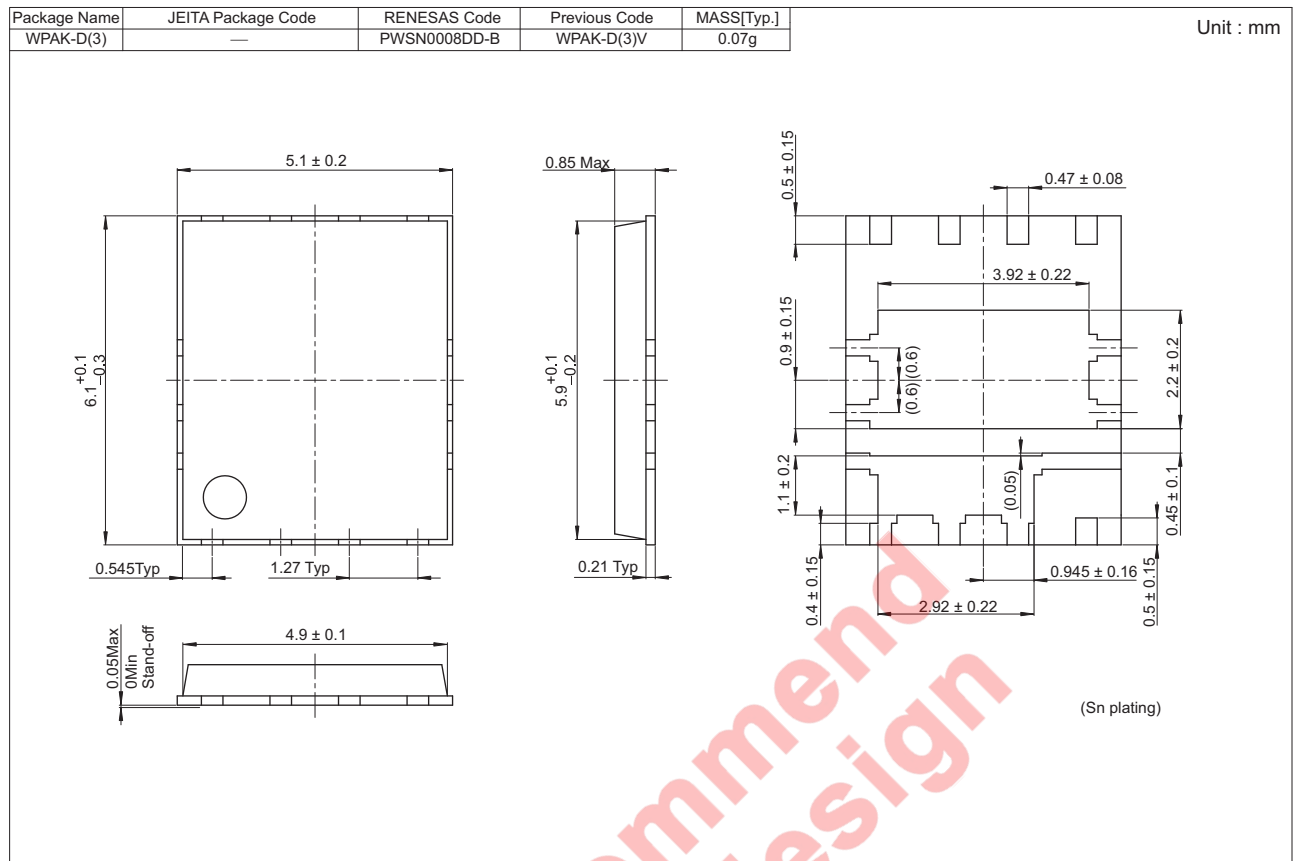
Switching Time Test Circuit



Switching Time Waveform



## Package Dimensions



## Ordering Information

| Orderable Part Number | Quantity | Shipping Container |
|-----------------------|----------|--------------------|
| RJK03P9DPA-00-J5A     | 3000 pcs | Taping             |

Note: The symbol of 2nd "-" is occasionally presented as "#".

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